

ON Semiconductor			10/15/2019	
Base Part		RS1KFP	HF	
Orderable Part		RS1KFP	Total weight (mg)	21.800223
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Clip	1.3299	Iron (Fe)	7439-89-6	0.10000752
		Copper (Cu)	7440-50-8	99.86999022
		Phosphorus (P)	7723-14-0	0.03000226
Die	2.021801	Silicon (Si)	7440-21-3	90.00027692
		Nickel (Ni)	7440-02-0	0.64984815
		Gold (Au)	7440-57-5	0.14984661
		Lead Bisilicate	65997-18-4	9.20002831
Die Attach Solder	0.41096	Silver (Ag)	7440-22-4	2.5
		Lead (Pb)	7439-92-1	92.5
		Tin (Sn)	7440-31-5	5
Lead Frame	12.308561	Iron (Fe)	7439-89-6	0.1
		Copper (Cu)	7440-50-8	99.87
		Phosphorus (P)	7723-14-0	0.03
Mold Compound-Black	5.728801	Ortho Cresol Novolac Resin	29690-82-2	10.05000872
		Carbon Black (C)	1333-86-4	0.49999991
		Fused Silica (SiO2)	60676-86-0	85.44999207
		Phenolic Resin (Novolac)	9003-35-4	3.99999993
Plating	0.0002	Tin (Sn)	7440-31-5	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				